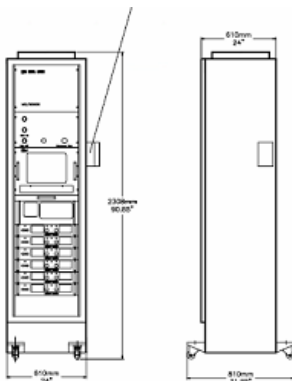
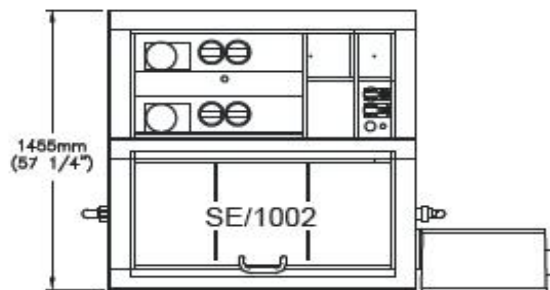
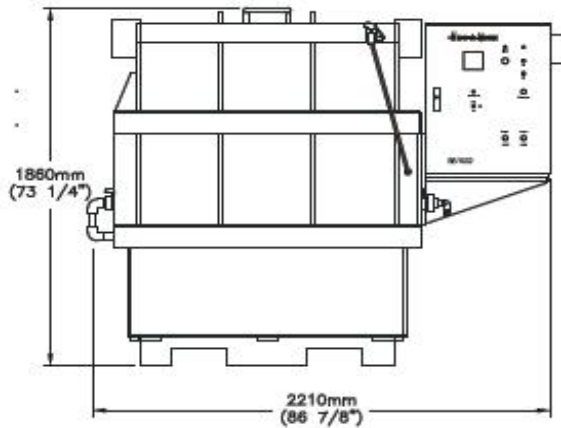


SE/1002 Electroplating System



Features

- Two Plating Cells per Tank
- High/Flow/Filtration (enhanced filtration yields fewer defects)
- Increased filtration, and speeds shim production
- Repeatability with uniform results and reduces cutting
- Precise control of shim thickness and thickness variation
- Ergonomically designed
- Easy process maintenance
- Available plating size TTV



Also included is an attached control rack with unified digital control computer and color flat screen display. (left)

SE/1002 Electroplating System
Specifications

Construction:	Polypropylene
Dimensions*:	Width: 86 ⁷ / ₈ in (2210 mm) Height: 73 ¹ / ₄ in (1860 mm) Depth: 57 ¹ / ₂ in (1455 mm) <i>* for example only, actual dimensions will vary based on custom plating size requirements</i>
Wafer Dimensions:	Custom holder up to 1000mm ²
Total Solution Volume:	200 gallons/ 950 liters
Heaters:	6 kW
Cooling:	Titanium Cooling Coil
Cells:	2
Pump:	1 hp. per cell
Rectifier:	Standard: 250 Amps 20 VDC Optional: Reverse pulse plating (specify range)
Filtration:	2 stage per cell Pre-filter: 5 micron DOE, 20 inches (508 mm) Final filter: 0.45 micron DOE, 20 inches (508 mm)
Flow:	50 lpm maximum (adjustable) per cell
Instrumentation:	Temperature: ±1° C dual setpoint
Utilities:	Electrical: 220 VAC, 3 Phase, 15kVA, 50/60Hz DI Water: Hose Barb ½ in NPT Male, 11 lpm Cooling: 11 lph, Pressure 45-60 psi, Temp. = 12° C (52° F)

